NFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

Applicant:

Z. Hu et al.

Attorney Docket No. SEMT116058

Application No.: 10/667,802

Group Art Unit: 1764

Filed:

September 22, 2003

Title:

PLATINUM ALLOY USING ELECTROCHEMICAL DEPOSITION

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*Examiner			Kind	Date	
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*Examiner: Initial if reference considered, whether or not citation is in conformance with M.P.E.P. § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

PLEMENTAL INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

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